

Title (en)  
DEVICE AND METHOD FOR PRODUCING A DEVICE

Title (de)  
VORRICHTUNG UND VERFAHREN ZUR HERSTELLUNG EINER VORRICHTUNG

Title (fr)  
DISPOSITIF ET PROCÉDÉ DE FABRICATION DU DISPOSITIF

Publication  
**EP 2379998 A1 20111026 (DE)**

Application  
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Abstract (en)  
[origin: WO2010072455A1] The invention relates to a device, particularly a sensor device, having a structural element, a carrier element and a housing, wherein the structural element is arranged on the carrier element, and wherein the structural element and the carrier element are arranged at least partially within the housing, and wherein the device furthermore has an intermediate housing that is arranged substantially between the housing and the structural element, wherein the intermediate housing comprises a pre-mold housing.

IPC 8 full level  
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See references of WO 2010072455A1

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EP 1376090 A1 20040102 - HITACHI LTD [JP]

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